

1A, 45V Trench Schottky Surface Mount Rectifier

FEATURES

- AEC-Q101 qualified
- Trench Schottky technology
- Low power loss, high efficiency
- Ideal for automated placement
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- Switching mode power supply (SMPS)
- Adapters
- Lighting application
- On-board DC/DC converter
- Automotive

MECHANICAL DATA

- Case: Micro SMA
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.006g (approximately)

KEY PARAMETERS			
PARAMETER	VALUE	TINU	
I _F	1	Α	
V_{RRM}	45	V	
I _{FSM}	25	Α	
T _{J MAX}	175	°C	
Package	Micro SMA		
Configuration	Single die		









Micro SMA



PARAMETER		SYMBOL	TSU1M45H	UNIT
Marking code on the device			Z1	
Repetitive peak reverse voltage		V _{RRM}	45	V
Reverse voltage, total rms value		V _{R(RMS)}	31	V
Forward current		I _F	1	А
Surge peak forward current single half sine-wave superimposed on rated load	t = 8.3ms		25	А
	t = 1.0ms	I _{FSM}	80	А
Junction temperature		T _J	-55 to +175	°C
Storage temperature		T _{STG}	-55 to +175	°C

Version: B2211





THERMAL PERFORMANCE			
PARAMETER	SYMBOL	TYP	UNIT
Junction-to-lead thermal resistance	$R_{\Theta JL}$	20	°C/W
Junction-to-ambient thermal resistance	R _{OJA}	73	°C/W
Junction-to-case thermal resistance	R _{eJC}	30	°C/W

Thermal Performance Note: Units mounted on PCB (5mm x 5mm Cu pad test board)

ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage ⁽¹⁾	$I_F = 0.5A, T_J = 25^{\circ}C$	V _F	0.47	-	V
	$I_F = 1.0A, T_J = 25^{\circ}C$		0.52	0.60	V
	$I_F = 0.5A, T_J = 125^{\circ}C$		0.37	-	V
	$I_F = 1.0A, T_J = 125$ °C		0.43	0.55	V
Reverse current @ rated V _R ⁽²⁾	T _J = 25°C	I _R	-	80	μA
	T _J = 125°C		-	3	mA
Junction capacitance	1MHz, $V_R = 4.0V$	CJ	156	-	pF

Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION			
ORDERING CODE	PACKAGE	PACKING	
TSU1M45H	Micro SMA	12,000 / Tape & Reel	

2 Version: B2211



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.1 Forward Current Derating Curve

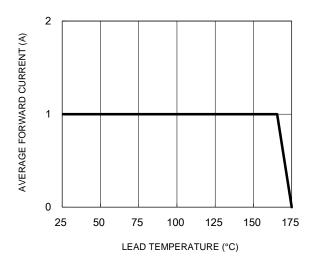


Fig.3 Typical Reverse Characteristics

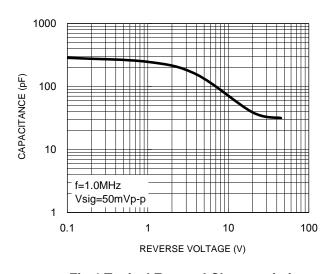
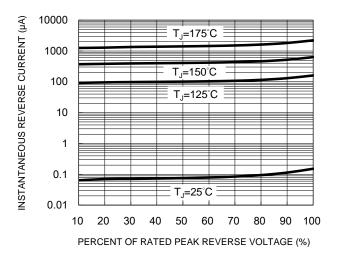


Fig.2 Typical Junction Capacitance

Fig.4 Typical Forward Characteristics



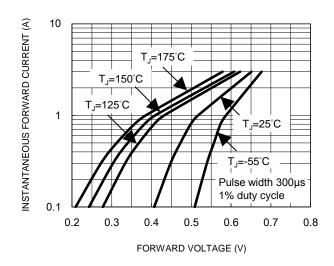
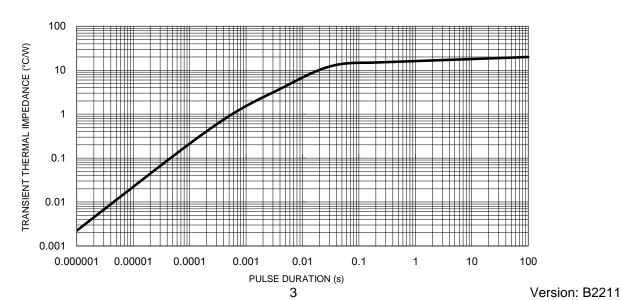


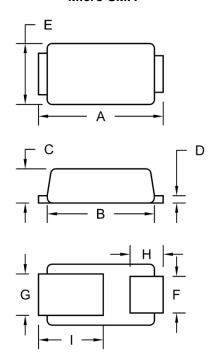
Fig.5 Typical Transient Thermal Impedance





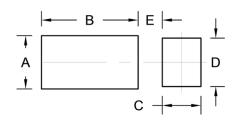
PACKAGE OUTLINE DIMENSIONS

Micro SMA



DIM.	Unit (mm)		Unit ((inch)
Dilvi.	Min.	Max.	Min.	Max.
Α	2.30	2.70	0.091	0.106
В	2.10	2.30	0.083	0.091
С	0.63	0.73	0.025	0.029
D	0.10	0.20	0.004	0.008
E	1.15	1.35	0.045	0.053
F	0.65	0.85	0.026	0.034
G	0.75	0.95	0.030	0.037
Н	0.55	0.75	0.022	0.030
I	1.10	1.50	0.043	0.059

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
Α	1.10	0.043
В	2.00	0.079
С	0.80	0.031
D	1.00	0.039
E	0.50	0.020

Notes:

This recommended land pattern is for reference purposes only. Please consult your manufacturing group to ensure your PCB design guidelines are met.

MARKING DIAGRAM



P/N = Marking Code

YW = Date Code



Notice

Specifications of the products displayed herein are subject to change without notice. TSC or anyone on its behalf, assumes no responsibility or liability for any errors or inaccuracies.

Purchasers are solely responsible for the choice, selection, and use of TSC products and TSC assumes no liability for application assistance or the design of Purchasers' products.

Information contained herein is intended to provide a product description only. No license, express or implied, to any intellectual property rights is granted by this document. Except as provided in TSC's terms and conditions of sale for such products, TSC assumes no liability whatsoever, and disclaims any express or implied warranty, relating to sale and/or use of TSC products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright, or other intellectual property right.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications. Customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify TSC for any damages resulting from such improper use or sale.

5 Version: B2211